

SOT274-1

plastic shrink dual in-line package; 64 leads (750 mil)

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SDIP64
Package type industry code	SDIP64
Package style descriptive code	SDIP (shrink dual in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-021
Mounting method type	T (through-hole mount)
Issue date	13-2-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	57.7	-	58.16	58.67	mm
E	package width	16.9	-	17	17.2	mm
A	seated height	[tbd]	-	5.84	5.84	mm
A ₂	package height	[tbd]	-	4.25	4.57	mm
n ₂	actual quantity of termination	-	-	64	-	



2. Package outline

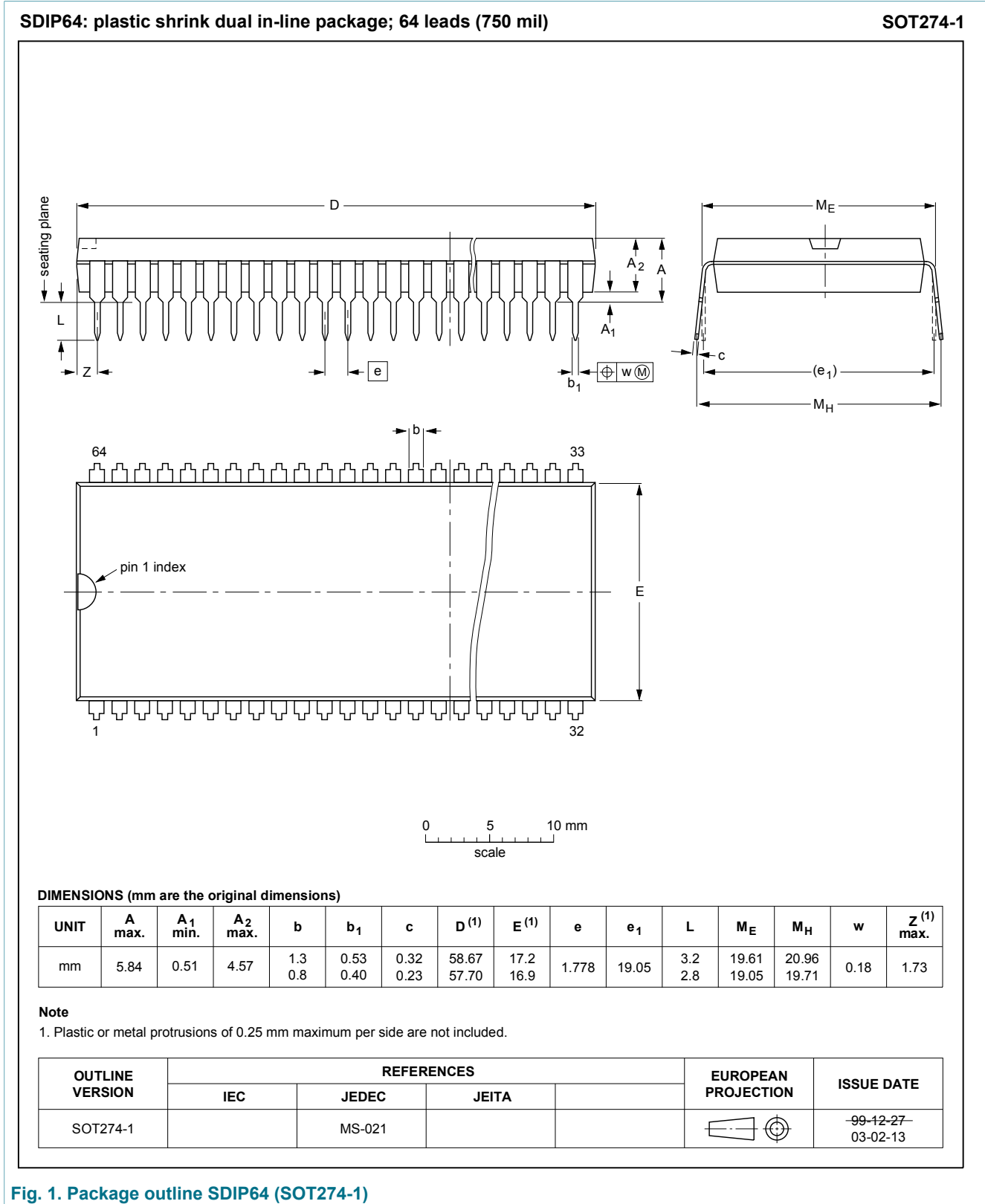


Fig. 1. Package outline SDIP64 (SOT274-1)

3. Legal information

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